

# CALL FOR ABSTRACTS



**20<sup>th</sup> European Advanced Technology  
Workshop  
ON MICROPACKAGING AND  
THERMAL MANAGEMENT  
LA ROCHELLE  
17<sup>th</sup> & 18<sup>th</sup> MARCH 2027**



**Conference Chairmen:** Jean-Yves SOULIER (Safran Data Systems)  
Bruno LEVRIER (Bruno Levrier Expertises)  
Jean-Pierre FRADIN (ICAM Toulouse)

**Technical Program Committee:**

Mohamad ABO RAS (BERLINER NANOTEST)                      Boguslaw WIECEK (Technical University of Lodz)  
Dave SAUMS (DS&A LLC)    Thomas HARDER (ECPE)  
Raphael SOMMET (XLIM Université de Limoges)              Sandrine FENEYROU (Safran Data Systems)  
Vincent AYEL (CNRS-ISAE ENSMA-Université de Poitiers)

We are pleased to open the call for papers of the 20<sup>th</sup> Advanced Technology Workshop on Micropackaging and Thermal Management that will be held in **La Rochelle on March 17<sup>th</sup> and 18<sup>th</sup>, 2027**. This yearly conference has grown year after year by the number of presented papers and attendees.

Be part of a successful 2027 edition and be sure to submit your abstract on time. The workshop sessions will include the following topics. Papers are invited in following areas:

- **Cooling solutions for microelectronics packaging and advanced electronic systems**
- **Thermal challenges in advanced packaging, chiplets, 2.5D/3D integration, HBM and heterogeneous systems**
- **Thermal management for AI, HPC, data centers, GPUs, accelerators and high-power servers**
- **Thermal interface materials, heat conductive materials and interface reliability**
- **Direct-to-chip liquid and immersion cooling, microchannel/manifold cooling and two-phase cooling**
- **Heat sinks, heat pipes, vapor chambers and phase change materials**
- **Advances in PCBs, embedded components and substrate-level thermal management**
- **Thermal modeling, CFD, digital twins, machine learning and AI-based optimization**
- **Thermal management of photonics, optical interconnects, co-packaged optics and optoelectronic components**
- **Power electronics, automotive, aerospace and harsh-environment thermal management**
- **Thermal characterization, test vehicles, in-situ sensing, IR thermography and reliability under thermal cycling**

Speakers will submit 200-300 words abstract detailing their presentation (20 minutes + 5 minutes for questions), no later than **5<sup>th</sup>, January 2027**.

Speakers pay a reduced registration fee (including MERCURE hotel accommodation for 2 nights and meals) and are also requested to attend the entire workshop to maximize opportunities of exchanging with other attendees and exhibitors.

Notification of acceptance by the Technical Committee: 20<sup>th</sup>, January 2027.

After notification of acceptance, you commit to attend the workshop or delegate someone else.

Please respond to IMAPS by e-mail: [imaps.france@orange.fr](mailto:imaps.france@orange.fr)

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